IN-LINE 3D AFM FOR CRITICAL DIMENSION AND SIDEWALL ROUGHNESS OF SI PHOTONIC WAVEGUIDE AND CORRELATION WITH ITS PROPAGATION LOSS

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3D AFM Measurement Methodology

- [•] Decoupled XY and Z scanner allows to tilt Z scanner head by $\pm 19^{\circ}$ and $\pm 38^{\circ}$
- Tilt Z scanner head allows probe to access waveguide sidewall
- Completed 3D geometry could be constructed by measuring 3 sides, top, left and right and stitching them together
- Single sidewall could be characterized as well by single tilt scan

In-line 3D AFM at imec



- Tool: NX3DM, Park Systems
- 24/7 operational at 300 mm P-line

lmec

SYSTEMS

- Fully automated for 300 mm wafer
- Scanning System
 - True non-contact measurement
 - Minimum probe-sample damage Long tip lifetime and good reliability



- Scanner Specification
 - XY scan area: 100 x 100 µm²
- Fully automated tool
 - Automatic Tip Exchanger
 - Fab Automation (SECS/GEM)

Sidewall Roughness Characterization



Evaluation of roughness, measured at the head angle of 0, 19 and 38° on *Flat Surface*







Sidewall Slope Angle Sidewall Roughness

Tilted measurements show a good agreement with roughness value at 0°.

Waveguide 3D Geometry and its Sidewall Roughness



In-line 3D AFM could accurately measure 3D geometry of Si waveguide as well as its sidewall roughness. Not only sidewall roughness characteristic but also its dimension could correlate with propagation loss of their waveguide